

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	8mΩ@10V	50A
	11mΩ@4.5V	

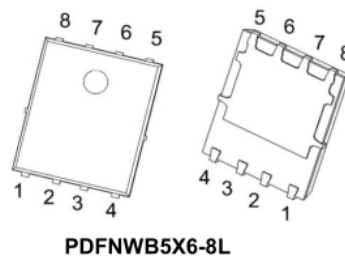
Feature

- $V_{DS} = 40V, I_D = 50A$
- $R_{DS(ON)} < 11m\Omega @ V_{GS}=10V$ (Typ. 8 mΩ)
 $R_{DS(ON)} < 17m\Omega @ V_{GS}=4.5V$ (Typ. 11 mΩ)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current

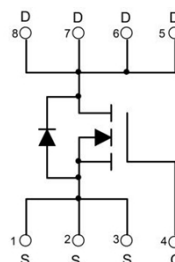
Application

- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

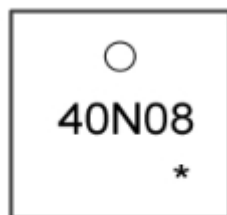
Package



Circuit diagram



Marking



40N08 : Product code
* : Month code.

Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^(Note 4)	I_D	50	A
Pulsed Drain Current ^(Note 1)	I_{DM}	200	A
Power Dissipation	$T_C=25^\circ\text{C}$	83.8	W
	$T_C=100^\circ\text{C}$	41.9	
Continuous Drain Current ^(Note 4)	$T_C=25^\circ\text{C}$	11	A
	$T_C=70^\circ\text{C}$	9	
Power Dissipation	$T_C=25^\circ\text{C}$	2.4	W
	$T_C=70^\circ\text{C}$	1.6	
Single Pulse Avalanche Energy (Note 6)	E_{AS}	72	mJ
Typical Thermal Resistance ^(Note 4,5)	Junction to Case	1.79	$^\circ\text{C}/\text{W}$
	Junction to Ambient	62.5	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$

Electrical characteristics

(T_A=25°C, unless otherwise noted)

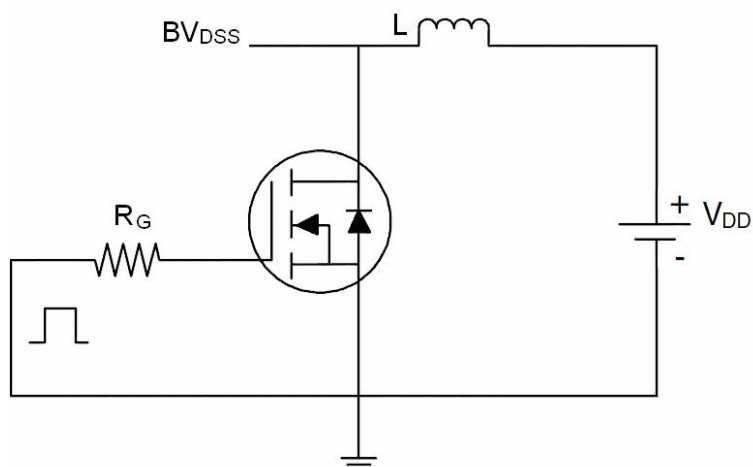
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV (BR)DSS	V _{GS} = 0V, I _D =250μA	40			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.5	2.5	V
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =12A		8	12	mΩ
		V _{GS} =4.5V, I _D =6A		11	18	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V,V _{GS} = 0V			1	uA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V , V _{DS} =0V			100	uA
Dynamic Characteristics ⁽³⁾						
Total Gate Charge	Q _g	V _{DS} =20V, I _D =8A, V _{GS} =10V ^(Note 2,3)		22		pF
Gate-Source Charge	Q _{gs}			4.2		
Gate-Drain Charge	Q _{gd}			4		
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1MHz		1013		pF
Output Capacitance	C _{oss}			134		
Reverse Transfer Capacitance	C _{rss}			88		
Switching Characteristics ⁽³⁾						
Turn-On Delay Time	T _{d(on)}	V _{DS} =15V, I _D =1A, V _{GS} =10V, R _G =3.3Ω		13		nS
Rise Time	T _r			14		
Turn-Off Delay Time	T _{d(off)}			45		
Fall Time	T _f			9		
Diode Characteristics						
Maximum Continuous Drain-Source Diode Forward Current	I _S				50	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V,I _S =1A		0.7	1	V

Notes:

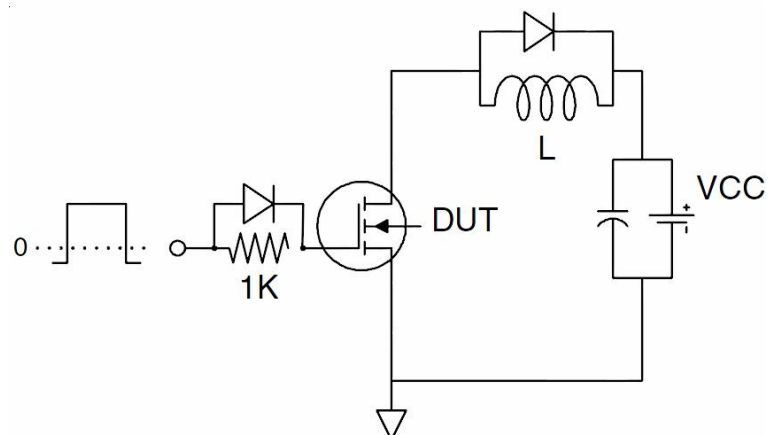
1. Pulse width < 300μs, Duty cycle < 2%.
2. Essentially independent of operating temperature typical characteristics.
3. Repetitive rating, pulse width limited by junction temperature T_J(MAX) = 150°C. Ratings are based on low frequency and duty cycles to keep initial T_J = 25°C.
4. The maximum current rating is package limited.
5. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz. square pad of copper.
6. The test condition is L = 0.1mH, I_{AS} = 38A, V_{DD} = 25V, V_{GS} = 10V, Starting T_J = 25°C.
7. Guaranteed by design, not subject to production testing.

Test Circuits

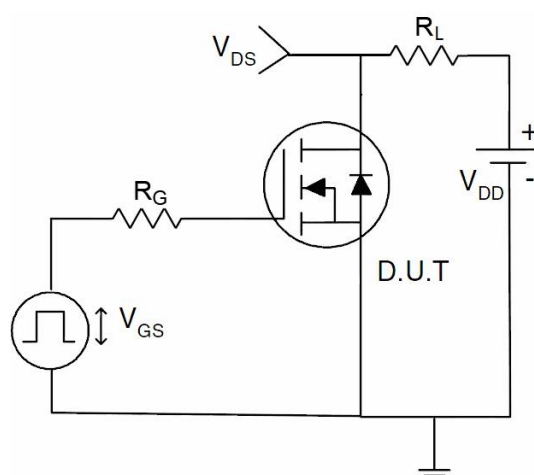
- EAS Test Circuits



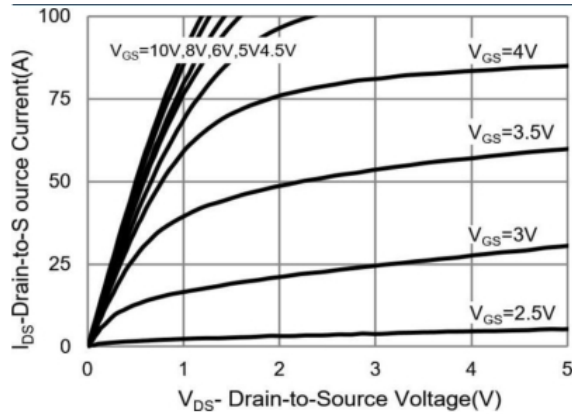
- Gate Charge Test Circuit



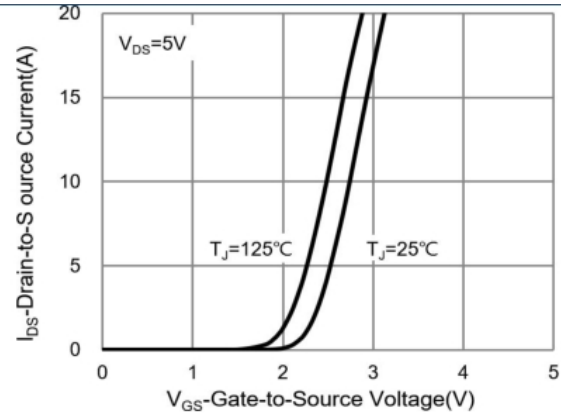
- Switch Time Test Circuit



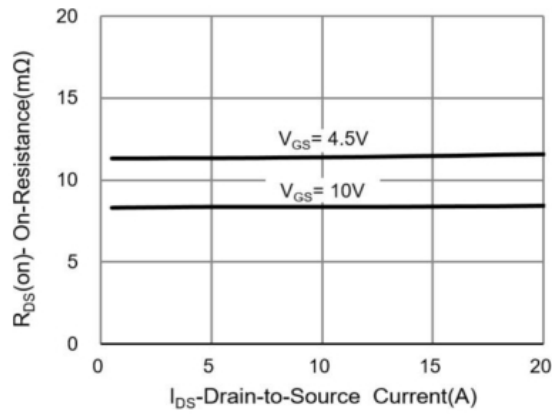
Typical Characteristics



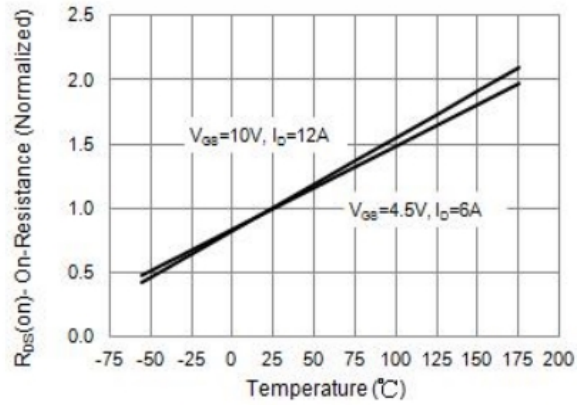
On-Region Characteristics



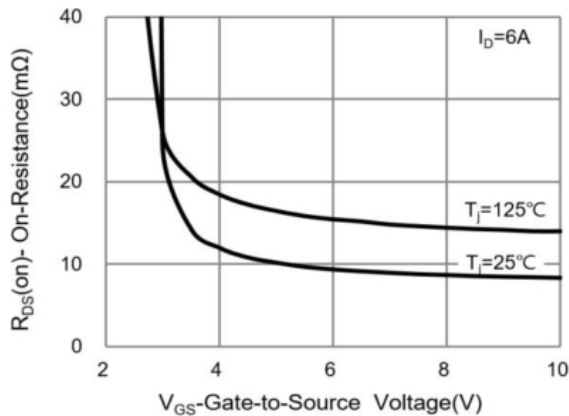
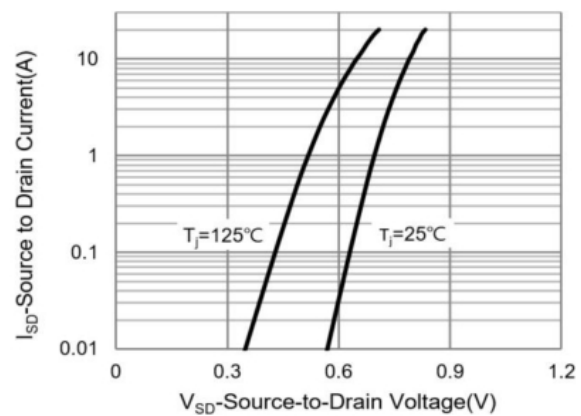
Transfer Characteristics



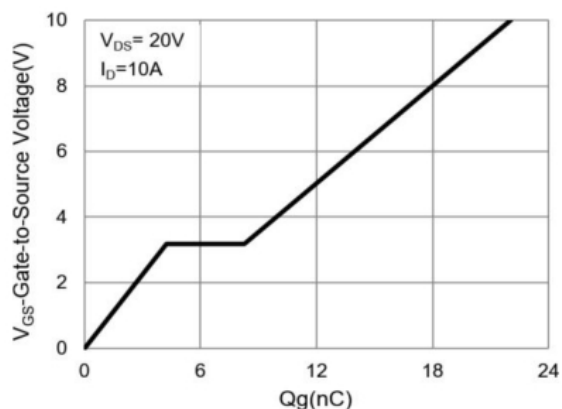
On-Resistance vs. Drain Current



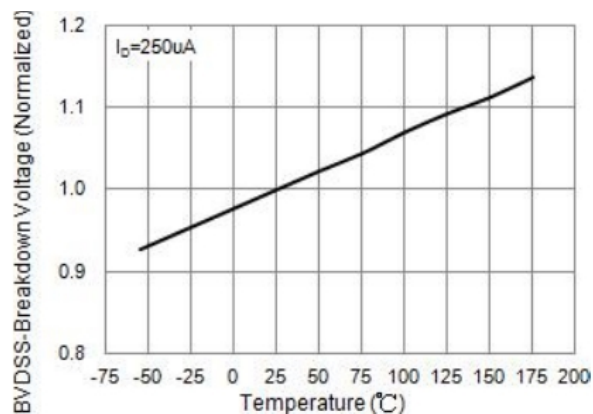
On-Resistance vs. Junction temperature


On-Resistance Variation with V_{GS}


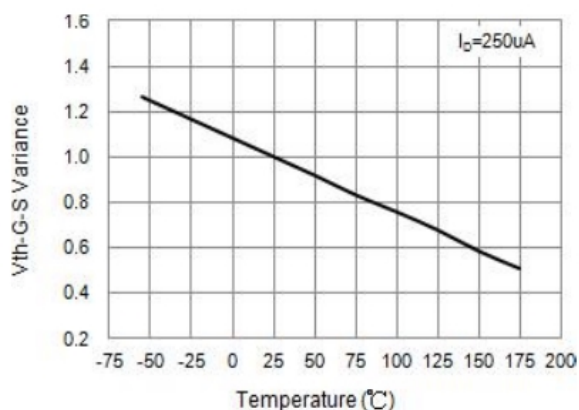
Body Diode Characteristics



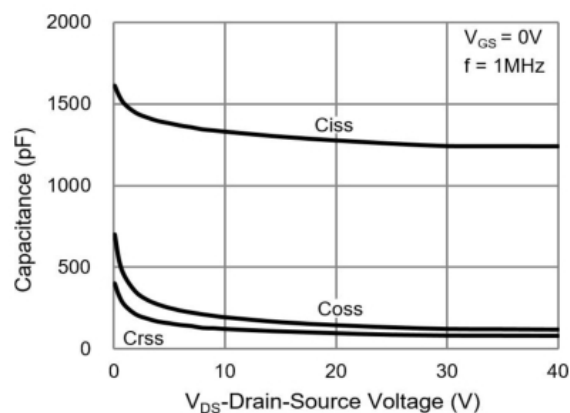
Gate-Charge Characteristics



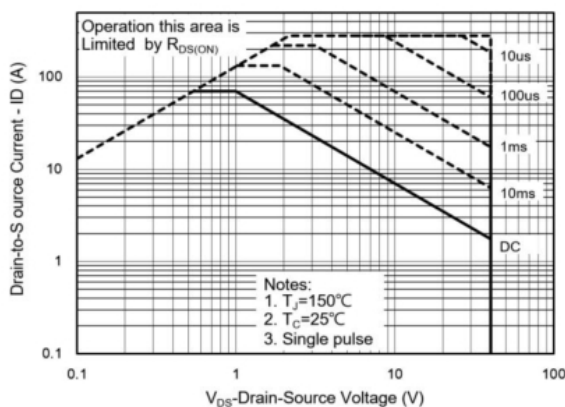
Breakdown Voltage Variation vs. Temperature



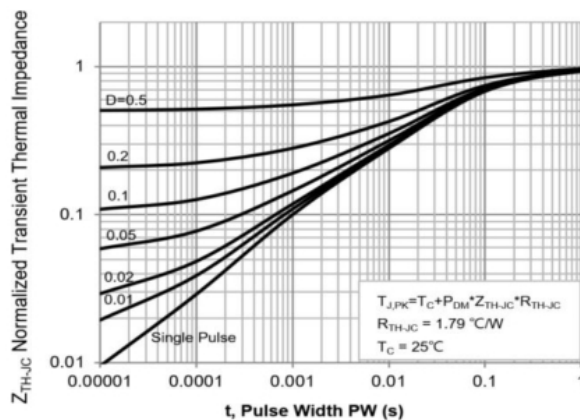
Threshold Voltage Variation with Temperature



Capacitance vs. Drain-Source Voltage

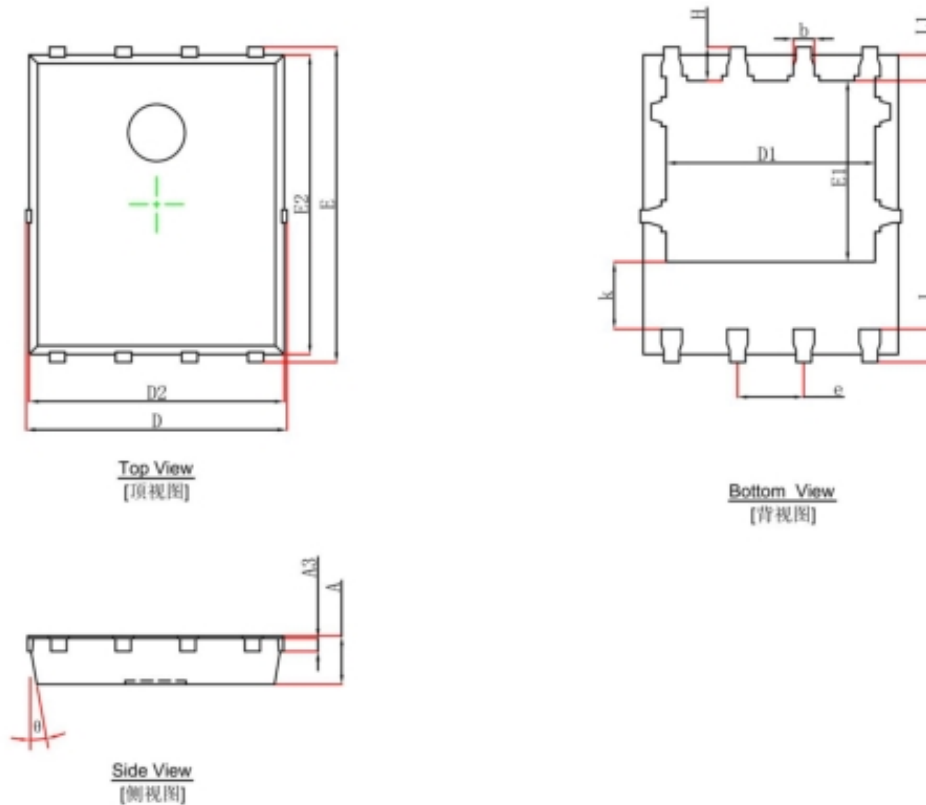


Maximum Safe Operating Area



Normalized Transient Thermal Impedance

PDFNWB5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°